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Product Specification

RoHS-6 Compliant 10Gb/s 850nm Multimode XENPAK Transponder FTLX8561E2

PRODUCT FEATURES

- Hot pluggable XENPAK form factor
- Total power consumption: 2.2 W maximum
- RoHS-6 compliant (lead-free)
- Temperature range 0°C to 70°C
- Transmission distance of 300m
- Uncooled 850nm VCSEL laser
- SC connector, multimode fiber
- Full duplex transmission mode
- Digital Optics Monitoring (DOM)
- Power supply: +5.0 V, +3.3 V
- Adaptable Power Supply (APS: +1.2 V)
- XAUI electrical interface
 - 4 x 3.125 Gb/s Ethernet
- Management and control via MDIO 2-wire bus
- 70-pin connector
- Separated signal/chassis ground



APPLICATIONS

- 10GBASE-SR 10G Ethernet

PRODUCT SELECTION

FTLX8561E2

I. Pin Descriptions

Signal Name	Level	I/O	Pin No.	Description
Management and Monitoring Ports				
MDIO	Open Drain	I/O	17	Management Data I/O. Requires external 10 - 22 k Ω pull-up to the APS on host.
MDC	1.2 V CMOS	I	18	Management Data Clock Input
PRTAD4	1.2 V CMOS	I	19	Port Address Input bit 4
PRTAD3	1.2 V CMOS	I	20	Port Address Input bit 3
PRTAD2	1.2 V CMOS	I	21	Port Address Input bit 2
PRTAD1	1.2 V CMOS	I	22	Port Address Input bit 1
PRTAD0	1.2 V CMOS	I	23	Port Address Input bit 0
LASI	Open Drain	O	9	Link Alarm Status Interrupt Output. Open Drain Compatible Output with 10 - 20 k Ω pull-up on host. Logic high = Normal Operation Logic low = Status Flag Triggered
RESET	Open Drain	I	10	Reset Input. Open Drain Compatible Input with 22 k Ω pull-up to APS internal to transponder. Logic high = Normal Operation Logic low = RESET
Vendor Specific			11,15,16,24	Vendor Specific Pins. Leave unconnected when not used.
TX ON/OFF	Open Drain	I	12	TX ON/OFF Input. Open Drain Compatible Input with 22 k Ω pull-up to APS internal to transponder. Logic high = Transmitter On Logic low = Transmitter Off
MOD DETECT		O	14	Pulled low inside transponder through a 1 k Ω resistor to Ground
Transmit Functions				
Reserved		I	68	Reserved For Future Use
Reserved		I	67	Reserved For Future Use
TX LANE 3– TX LANE 3+	AC-coupled, Internally biased differential XAUI	I	65	Module XAUI Input Lane 3–
		I	64	Module XAUI Input Lane 3+
TX LANE 2– TX LANE 2+		I	62	Module XAUI Input Lane 2–
		I	61	Module XAUI Input Lane 2+
TX LANE 1– TX LANE 1+		I	59	Module XAUI Input Lane 1–
		I	58	Module XAUI Input Lane 1+
TX LANE 0– TX LANE 0+		I	56	Module XAUI Input Lane 0–
	I	55	Module XAUI Input Lane 0+	

Receive Functions				
Reserved		O	38	Reserved For Future Use
Reserved		O	39	Reserved For Future Use
RX LANE 0+	AC-coupled, Internally biased differential XAUI	O	41	Module XAUI Output Lane 0+
RX LANE 0-		O	42	Module XAUI Output Lane 0-
RX LANE 1+		O	44	Module XAUI Output Lane 1+
RX LANE 1-		O	45	Module XAUI Output Lane 1-
RX LANE 2+		O	47	Module XAUI Output Lane 2+
RX LANE 2-		O	48	Module XAUI Output Lane 2-
RX LANE 3+		O	50	Module XAUI Output Lane 3+
RX LANE 3-		O	51	Module XAUI Output Lane 3-
DC Power				
GND	0 V DC		1, 2, 3, 33, 34, 35, 36, 37, 40, 43, 46, 49, 52, 53, 54, 57, 60, 63, 66, 69, 70	Ground connection for signal ground on the module
APS	+1.2 V		7, 8, 28, 29	Input from Adaptive Power Supply
APS SENSE	+1.2 V		27	APS Sense Output. Connected to the APS input inside transponder.
APS SET			25	Feedback input from APS. Connected to GND through a 1180Ω resistor inside the transponder.
3.3 V	+3.3 V DC		5, 6, 30, 31	DC Power Input, +3.3 V DC, Nominal
5.0 V	+5.0 V DC		4, 32	DC Power Input, +5.0 V DC, Nominal
Reserved			26	Reserved for APD.
Reserved			13	Reserved.

Electrical Pad Layout

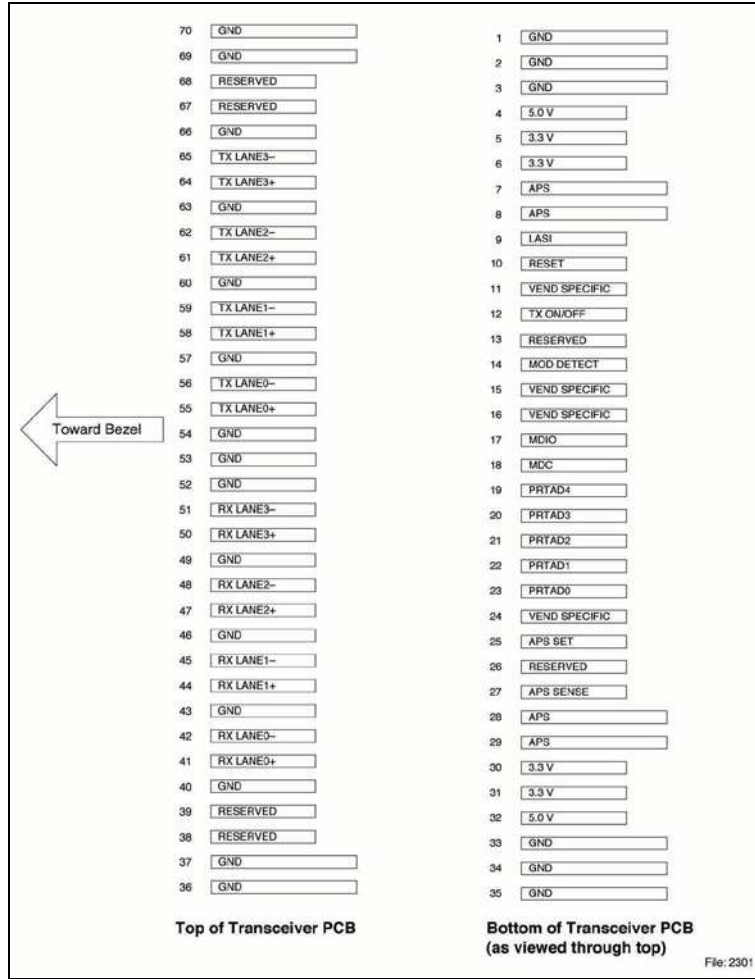


Fig 1-XENPAK Transponder Electrical Pad Layout

II. Absolute Maximum Ratings

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Storage Ambient Temperature ¹⁾	T_S	-40	85	°C
Operating Case Temperature ¹⁾	T_C	0	70	°C
Supply Voltage +5.0 V	V_5	0	6	V
Supply Voltage +3.3 V	V_3	0	4	V
Supply Voltage APS	V_{aps}	0	1.5	V
Static Discharge Voltage, All Pins ²⁾	ST_d		500	V
Average Receive Optical Power	RxP_{max}		1.5	dBm

Notes:

- 1) Non-condensing.
- 2) HBM.

Exceeding any one of these values may permanently destroy the device.

III. Electrical Characteristics

Recommended Operating Conditions

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Operating Case Temperature ¹⁾	T_C	0		70	°C
Transponder Total Power Consumption	P			2.2	W
Supply Voltage +5.0 V	V_{CC5}	4.75	5.0	5.25	V
Supply Current +5.0 V	I_{CC5}		157	190	mA
Supply Voltage +3.3 V	V_{CC3}	3.14	3.3	3.47	V
Supply Current +3.3 V	I_{CC3}		55	72	mA
Supply Voltage APS	$V_{CC\text{aps}}$	1.152	1.2	1.248	V
Supply Current APS	$I_{CC\text{aps}}$		830	850	mA

¹⁾ Measured at reference thermal location, see **Figure 2**.
See also **Environmental Performance**.

Electrical DC Characteristics

(V_{CC5} = 4.75 V to 5.25 V, V_{CC3} = 3.14 V to 3.47 V, $V_{CC\text{aps}}$ = 1.152 V to 1.248 V, T_C = 0°C to 70°C)

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
1.2 V CMOS (1.8 V CMOS Compatible¹⁾) I/O DC Characteristics (PRTAD; LASI; RESET; TX_ONOFF)					
External Pull-up Resistor for Open Drain	R_{pullup}	10		22	k Ω
Output High Voltage ²⁾	V_{oh}	1			V
Output Low Voltage ²⁾	V_{ol}			0.15	V
Input High Voltage	V_{ih}	0.84		1.5	V
Input Low Voltage	V_{il}			0.36	V
Input Pull-down Current ³⁾	I_{pd}	20		120	μ A
XAUI I/O DC Characteristics (TXLANE[0..3]; RXLANE[0..3])					
Differential Input Amplitude (pk-pk) ⁴⁾	$V_{\text{in_xaui}}$	200		2500	mV
Differential Output Amplitude (pk-pk) ⁴⁾	$V_{\text{out_xaui}}$	800		1600	mV
MDIO I/O DC Characteristics (MDIO; MDC)					
Output Low Voltage ⁵⁾	V_{OL}	-0.3		0.2	V
Output Low Current	I_{OL}			20	mA
Input High Voltage	V_{IH}	0.84		1.5	V
Input Low Voltage	V_{IL}	-0.3		0.36	V
Pull-up Supply Voltage	V_{PU}	0.84	1.2	1.5	V
Input Capacitance	C_{IN}			10	pF
Load Capacitance	C_{LOAD}			470	pF
External Pull-up Resistance	R_{LOAD}	200			Ω

¹⁾ For 1.8 V CMOS V_{oh} = 1.65 V min., V_{ol} = 0.15 V max., V_{ih} = 1.17 V min., V_{il} = 0.63 V max.

²⁾ $R_{\text{pull-up}}$ = 10 k Ω to 1.8 V.

³⁾ V_{in} = 1.8 V.

⁴⁾ AC coupled.

⁵⁾ I_{OL} = 100 μ A

Electrical AC Characteristics(V_{CC5} = 4.75 V to 5.25 V, V_{CC3} = 3.14 V to 3.47 V, V_{CCaps} = 1.152 V to 1.248 V, T_C = 0°C to 70°C)

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
XAUI Input AC Characteristics (TXLANE[0..3])					
Baud Rate Fibre Channel Ethernet	R _{XAUIIN}		3.1875 3.125		Gbit/s
Baud Rate Tolerance	R _{TOLXAUI}	-100		100	ppm
Differential Input Impedance	Z _{INXAUI}	80	100	120	Ω
Differential Return Loss ¹⁾	S ₁₁	10			dB
Input Differential Skew ²⁾	t _{SKEWIN}			75	ps
Jitter Amplitude Tolerance ³⁾	J _{XAUITOL}			0.65	UI _{p-p}
XAUI Output AC Characteristics (RXLANE[0..3])					
Baud Rate Fibre Channel Ethernet	R _{XAUIOUT}		3.1875 3.125		Gbit/s
Baud Rate Variation	R _{XAUIVAR}	-100		100	ppm
XAUI Eye Mask (far-end)	According to IEEE 802.3ae				
Output Differential Skew	t _{SKEWOUT}			15	ps
Output Differential Impedance	Z _{OUTXAUI}	80	100	120	Ω
Differential Output Return Loss ¹⁾	S ₂₂	10			dB
Total Jitter ⁴⁾	TJ _{XAUI}			0.35	UI
Deterministic Jitter ⁴⁾	DJ _{XAUI}			0.37	UI
Power-On Reset AC Characteristics					
Power-On Reset and TX_ONOFF Characteristics	According to XENPAK MSA Issue 3.0, 2002-9-18				
MDIO I/O AC Characteristics (MDIO; MDC)					
MDIO Data Hold Time	t _{HOLD}	10			ns
MDIO Data Setup Time	t _{SU}	10			ns
Delay from MDC Rising Edge to MDIO Data Change	t _{DELAY}			300	ns
MDC Clock Rate	f _{MAX}			2.5	MHz

¹⁾ 100 MHz to 2.5 GHz.²⁾ At crossing point.³⁾ Per IEEE Std 802.3ae.⁴⁾ At near-end, No pre-equalization, 1 UI = 320 ps.

IV. Optical Characteristics

($V_{CC5} = 4.75 \text{ V to } 5.25 \text{ V}$, $V_{CC3} = 3.14 \text{ V to } 3.47 \text{ V}$, $V_{CC\text{aps}} = 1.152 \text{ V to } 1.248 \text{ V}$, $T_C = 0^\circ\text{C to } 70^\circ\text{C}$, BER 1E-12, Bit Rate 10.3125)

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Transmitter					
Launch Power in OMA ¹⁾	$P_{O\text{-OMA}}$	-2.8	-1.5		dBm
Average Launch Power	$P_{O\text{-Avg}}$	-5		-1	dBm
Transmitter and Dispersion Penalty	TDP			3.9	dB
Center Wavelength Range ¹⁾	$\lambda_{C\text{-Tx}}$	840	850	860	nm
RMS Spectral Width ¹⁾	σ_I		0.4	0.45	nm
Extinction Ratio	ER	3	5.5		dB
Relative Intensity Noise ₁₂ OMA	RIN			-128	dB/Hz
Eye Mask Definition	According to IEEE 802.3ae				
Encircled Flux	EF	at $19 \mu\text{m} \geq 86\%$, at $4.5 \mu\text{m} \leq 30\%$			
Optical Return Loss Tolerance	ORL_T			12	dB
Average Launch Power of OFF Transmitter	$P_{O\text{-OFF}}$			-30	dBm
Receiver					
Stressed Receiver Sensitivity in OMA	$P_{IN\text{-S}}$			-7.5	dBm
Receiver Sensitivity in OMA ²⁾	P_{IN}			-11.1	dBm
Average Receive Power	$P_{IN\text{-max}}$			-1	dBm
Signal Detect Deassert Level	P_{SDL}			-14.5	dBm
Signal Detect Assert Level	P_{SD}	-18.0			dBm
Signal Detect Hysteresis	P_{SD}	0.5	1.5		dB
Receiver Reflectance	REF_{RX}			-12	dB
Center Wavelength Range	$\lambda_{C\text{-RX}}$	840		860	nm

¹⁾ Conforms to IEEE triple trade-off between center wavelength, RMS spectral width and minimum OMA.

²⁾ Receiver sensitivity, which is defined for an ideal input signal is informative only.

V. General Specifications

Optical Interface Standard Specifications

Standard	Fiber Type	Minimum Modal Bandwidth at 850 nm (MHz*km)	Operating Range ¹⁾ (meters)
IEEE	62.5 μm MMF	160	2 to 26
	50 μm MMF	400	2 to 66
	50 μm MMF	500	0.5 to 82
	50 μm MMF	2000	0.5 to 300

Notes:

1) Operating range as defined by IEEE standards. Longer reach possible depending upon link implementation.

Environmental Performance

Operating case temperature: 0°C to +70°C
 Operating humidity: 0% -95% RH non-condensing

Fibers and Connectors

The transponder has SC receptacles for both Tx and Rx. The transponder is designed for multimode SC cables, 0° polished endface (PC).

70-pin Connector

The module interface connector is a 70-pin, printed circuit board edge connection with a 0.5 mm pitch. The appropriate mating connector for the customer PCB is a 70-pin SMT, dual row, right angled, edge connector, 0.5 mm pitch (Tyco Electronics part number 1367337-1, Molex part number 74441-0003 or equivalent).

Rail and Mechanical Mounting Requirements

The XENPAK rail system required to mount the XENPAK module is fully defined by the MSA.

Aqueous Wash

Finisar XENPAK transponders are neither solderable nor aqueous washable and are not intended for these processes.

VI. Regulatory Compliance

Feature	Standard	Comments
ESD: Electrostatic Discharge to the Electrical Pins (HBM)	EIA/JESD22-A114-B (MIL-STD 883D Method 3015.7)	Class 1a (> 500 V)
Immunity: Against Electrostatic Discharge (ESD) to the Module Receptacle	EN 61000-4-2 IEC 61000-4-2	Discharges ranging from ± 2 kV to ± 25 kV to the front end / faceplate / receptacle cause no damage to module (under recommended conditions).
Immunity: Against Radio Frequency Electromagnetic Field	EN 61000-4-3 IEC 61000-4-3	With a field strength of 10 V/m, noise frequency ranges from 10 MHz to 2 GHz. No effect on module performance between the specification limits.
Emission: Electromagnetic Interference (EMI)	FCC 47 CFR Part 15, Class B EN 55022 Class B CISPR 22	Noise frequency range: 30 MHz to 40 GHz Radiated emission does not exceed specified limits when measured with module inside a shielding enclosure with a MSA conforming cutout.

Eye Safety

Finisar FTLX8561E2 transponders are Class 1 Laser Products. They are certified per the following standards:

Feature	Agency	Standard	Certificate Number
Laser Eye Safety	FDA/CDRH	CDRH 21 CFR 1040 and Laser Notice 50	9210176-77
Laser Eye Safety	TÜV	EN 60825-1: 1994+A11:1996+A2:2001 IEC 60825-1: 1993+A1:1997+A2:2001 IEC 60825-2: 2000, Edition 2	R 72052602
Electrical Safety	TÜV	EN 60950	R 72052602
Electrical Safety	UL/CSA	CLASS 3862.07 CLASS 3862.87	1439230

Copies of the referenced certificates are available at Finisar Corporation upon request.

VII. DOM Parameters

Parameter	Values			Unit
	min.	typ.	max.	
Transponder Temperature Monitor Accuracy ¹⁾	-5		+5	°C
Laser Bias Current Monitor Accuracy ²⁾	-10		+10	%
Transmit Power Monitor Accuracy ³⁾	-3		+3	dB
Receive Power Monitor Accuracy ³⁾	-3		+3	dB

¹⁾ 0 to 70°C case temperature.

²⁾ 0 to 12.5 mA.

³⁾ -8.2 dBm to +0.5 dBm.

VIII. Mechanical Specifications

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Module Retention Force (latch strength)	F _{RET}		200		N
Module Insertion Force	F _{IN}		40		N
Module Extraction Force (with kick-out)	F _{EXT-K}		16		N
Module Extraction Force (without kick-out)	F _{EXT}		25		N

Pull Sleeve front face color is beige.

Package Outline

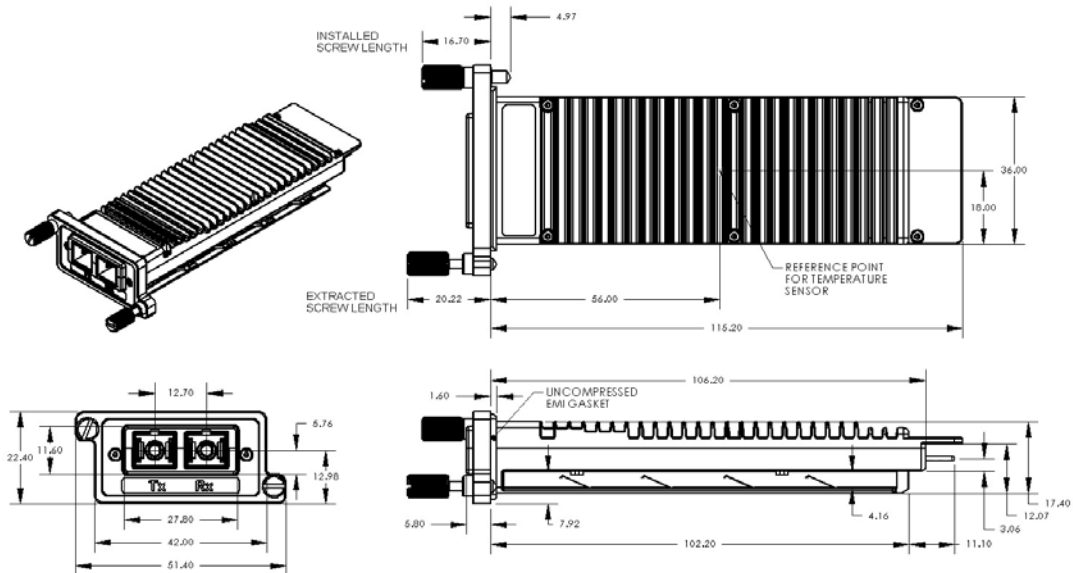


Figure 2 - XENPAK Mechanical Dimensions

IX. References

The following references are provided for informational purposes only. The parameters and operational behavior outlined in this specification describe the complete functionality of the 10G Transponder. Contact Finisar for any items concerning the operational characteristics of this device.

- IEEE Std 802.3ae-2002 clause 52, 10GBASE-SR
- XENPAK MSA Issue 3.0

X. For More Information

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